



**STS Multiplex ICP
Deep Reactive Ion Si Etcher
SN 10643
Vintage 1997**

**STS Multiplex ICP
Deep Reactive Ion Si Etcher
located Nijmegen the Netherlands**

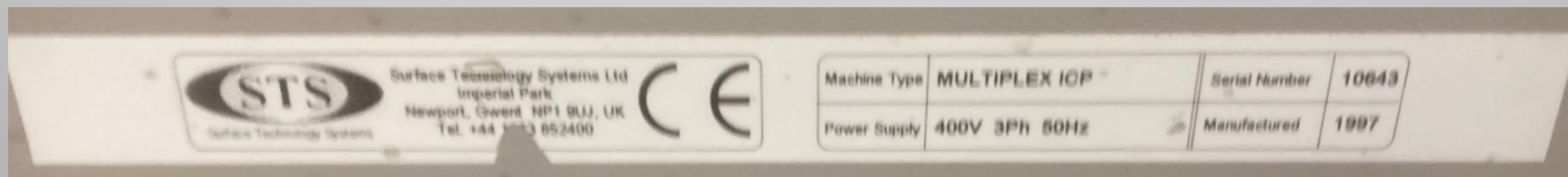
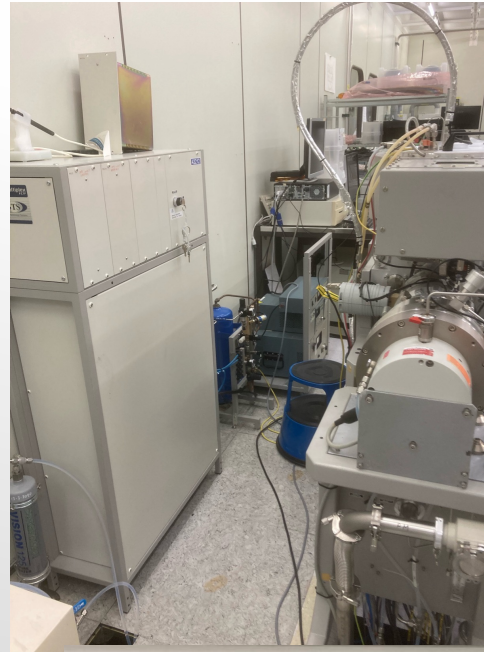
STS Deep Reactive Ion Si Etcher (Bosch Process)
Vintage 1997
200mm

The STS Multiplex DRIE uses the Bosch process for etching silicon deep and anisotropic. In addition to the platen RF power supply for RIE the system also has an ICP RF source for independently controlling the plasma density from the DC Bias.

The system uses a water cooled electrode and He backside flow to keep the sample cool. This system is designed to etch a 200 mm wafer.



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